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FIG. 1

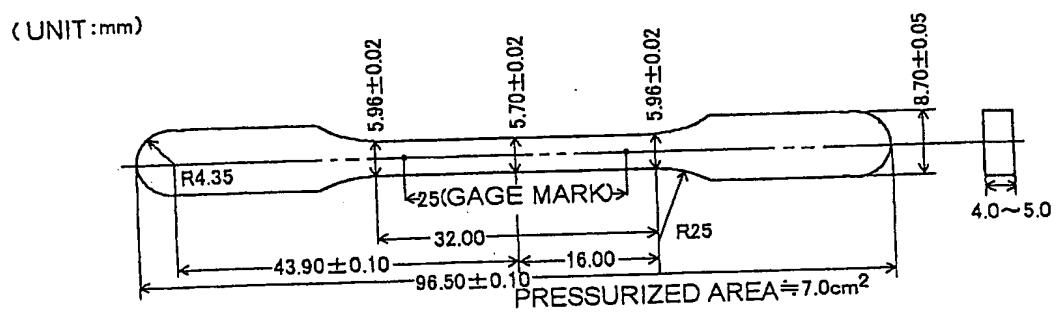


FIG. 2

THE TENSILE STRENGTH OF CuNiSi AND
 Cu_3SnNiSi SINTERED MATERIALS (σ_b)

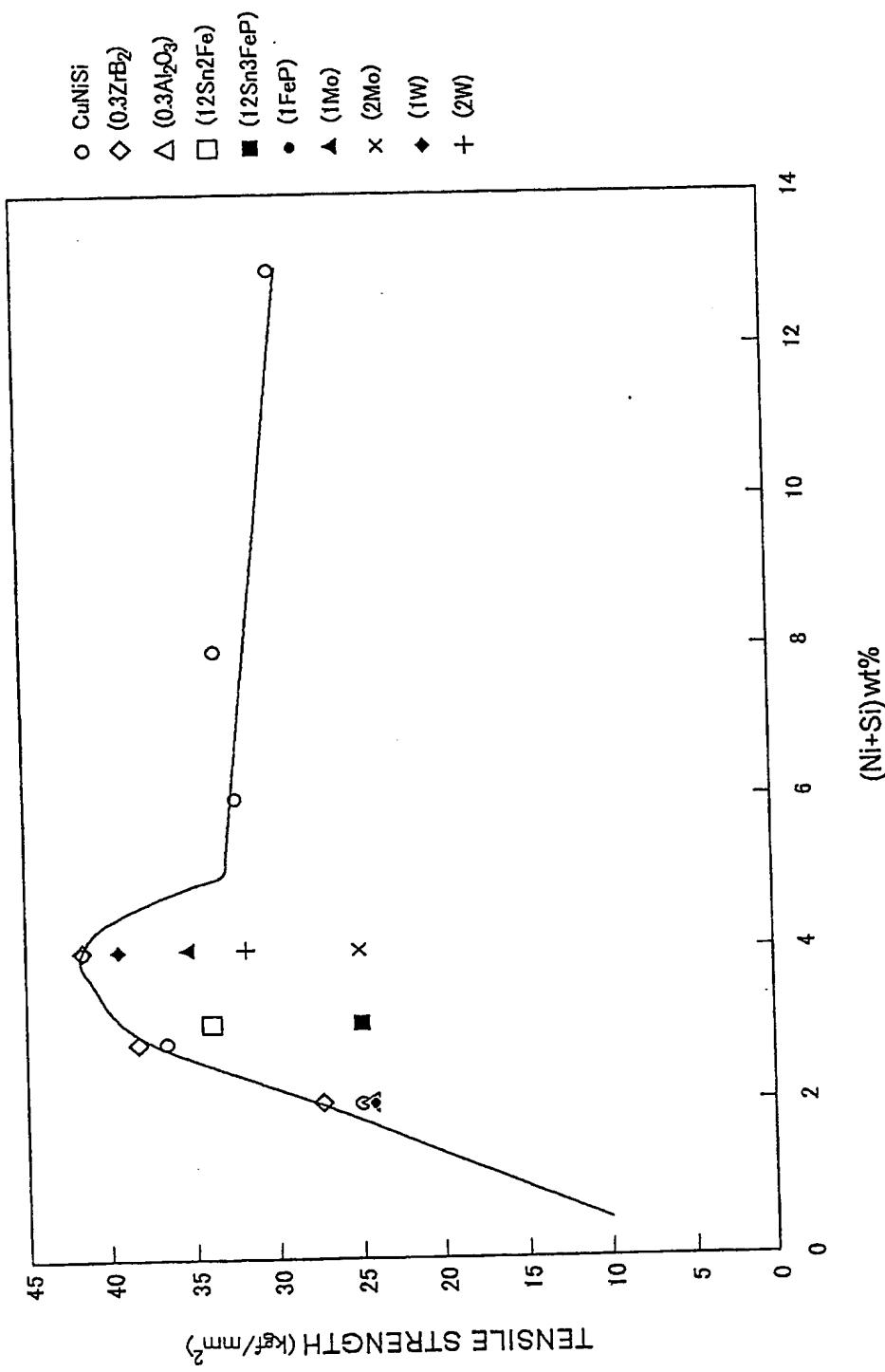
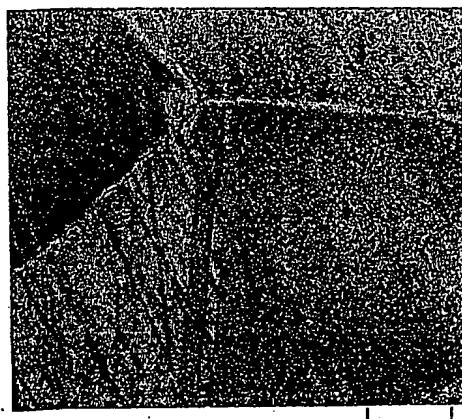
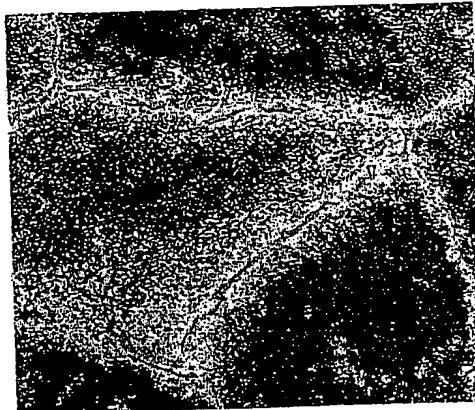


FIG. 3

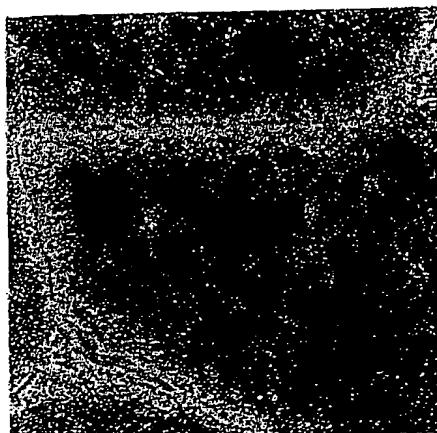
THE STRUCTURES OF Cu-Ni-Si BASED SINTERED COMPACTS
(A MAGNIFICATION OF $\times 400$)
(SINTERING CONDITION $1100^{\circ}\text{C} \times 1\text{HR}$)



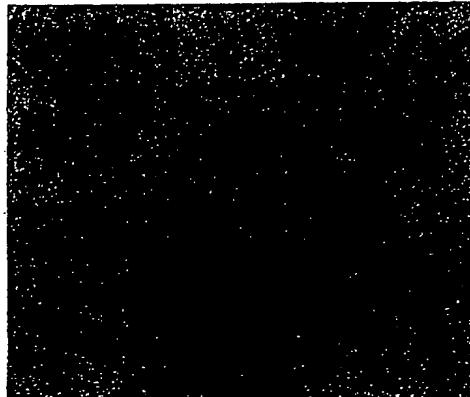
a) Cu-3Ni-1Si $25 \mu\text{m}$



b) Cu-4.5Ni-1.5Si



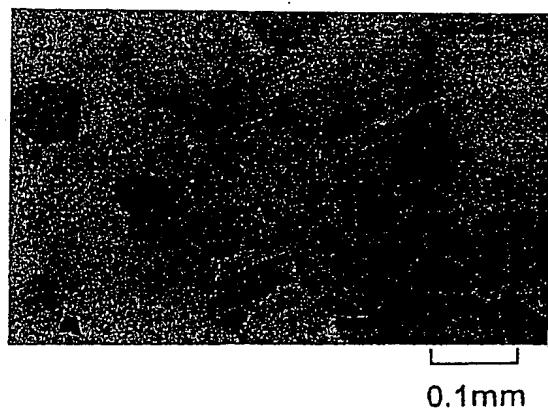
c) Cu-6Ni-2Si



d) Cu-10Ni-3.33Si

FIG. 4

THE STRUCTURE OF A Cu-3Ni-1Si-0.5SiO₂ BASED
SINTERED COMPACT
(A MAGNIFICATION OF ×100)
(1100°C × 1HR)



0.1mm

FIG. 5

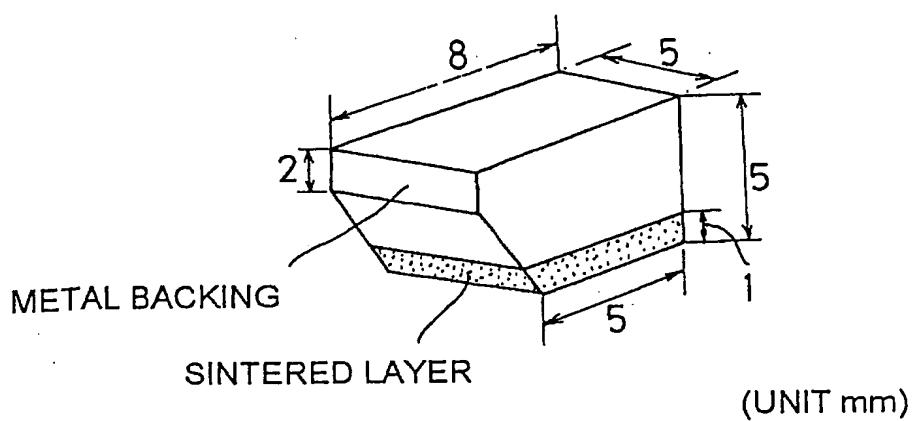


FIG. 6

THE STRUCTURE OF A Cu-10Sn-10Ni-0.55FeP-3Pb (B16)
BASED SINTERED COMPACT
(850°C × 1HR)

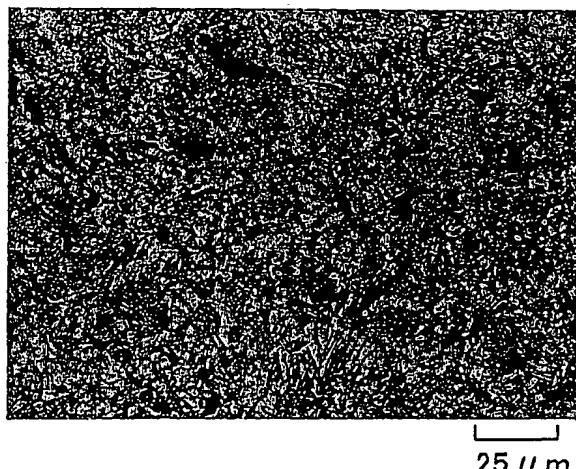


FIG. 7

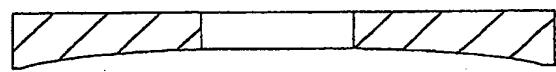


FIG. 8

